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# 1SS226

**PRV : 85 Volts  
Io : 100 mA**

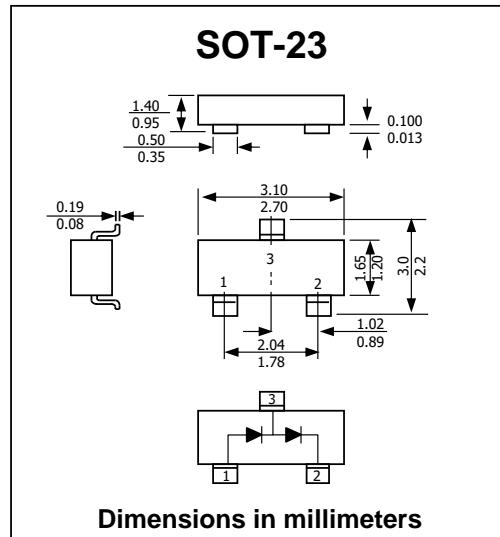
## FEATURES :

- \* Small package
- \* Low forward voltage
- \* Fast reverse recovery time
- \* Small total capacitance
- \* Ultra high speed switching application
- \* Pb / RoHS Free

## MECHANICAL DATA :

- \* Case : SOT-23 plastic Case
- \* Marking Code : A7

## SILICON EPITAXIAL PLANAR DIODE



Dimensions in millimeters

## MAXIMUM RATINGS AND THERMAL CHARACTERISTICS (Ta = 25 °C)

Parameter	Symbol	Value	Unit
Maximum Peak Reverse Voltage	V <sub>RM</sub>	85	V
Reverse Voltage	V <sub>R</sub>	80	V
Maximum Peak Forward Current	I <sub>FM</sub>	300	mA
Average Forward Current	I <sub>F(AV)</sub>	100	mA
Surge Current (10 ms)	I <sub>FSM</sub>	2	A
Power Dissipation	P <sub>D</sub>	350	mW
Junction Temperature	T <sub>J</sub>	150	°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C

## Thermal Characteristics

Parameter	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient <sup>1)</sup>	R <sub>θJA</sub>	357	°C/W

<sup>1)</sup> Device mounted on FR-4 substrate PC board, with minimum recommended pad layout.

## ELECTRICAL CHARACTERISTICS (Ta = 25 °C)

Parameter	Test Condition	Symbol	Min.	Max.	Unit
Reverse Breakdown Voltage	I <sub>R</sub> = 10 µA	V <sub>(RB)R</sub>	80	-	V
Forward Voltage	I <sub>F</sub> = 100 mA	V <sub>F</sub>	-	1.2	V
Reverse Current	V <sub>R</sub> = 80 V	I <sub>R</sub>	-	0.5	µA
Total Capacitance	V <sub>R</sub> = 0 V, f = 1 MHz	C <sub>T</sub>	-	3	pF
Reverse Recovery Time	I <sub>R</sub> = 10 mA	Tr <sub>r</sub>	-	4	ns

## RATINGS AND CHARACTERISTIC CURVES ( 1SS226 )

Fig 1. Power Derating Curve

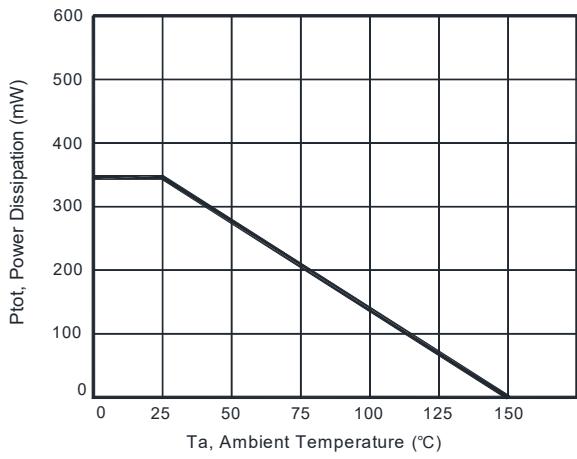


Fig 2. Capacitance Characteristics

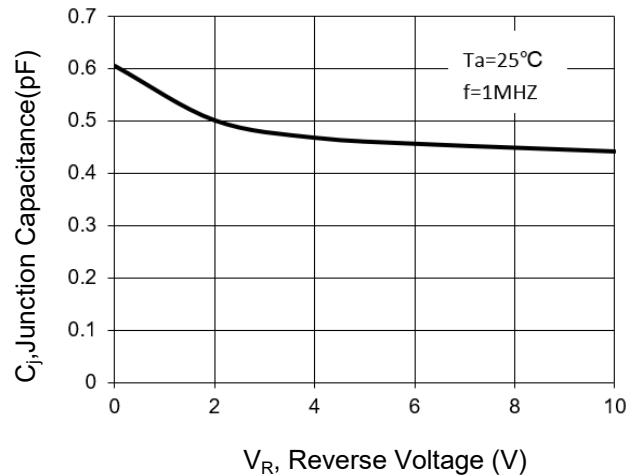


Fig 3. Reverse Characteristics

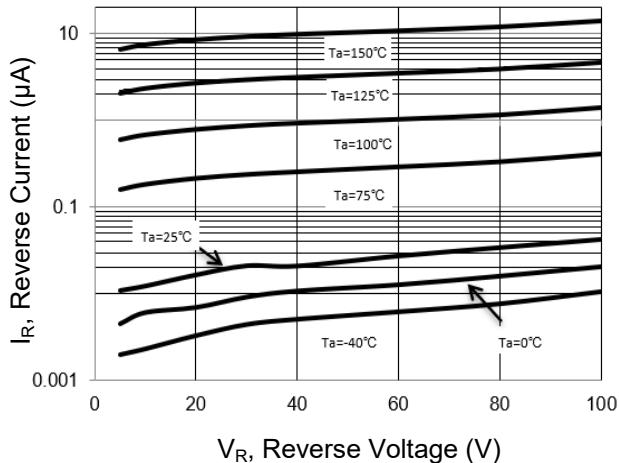


Fig 4. Forward Characteristics

